

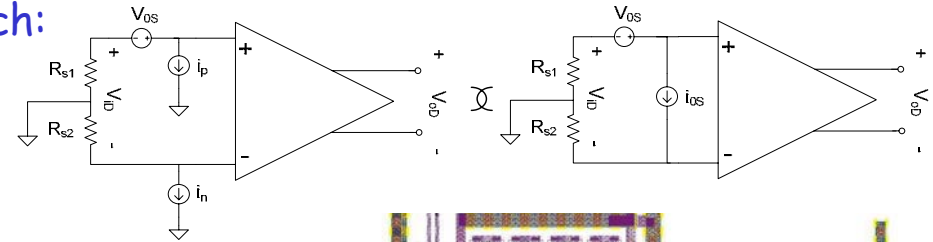


# Offset on SPD

# Offset: preamplifier

- Preamplifier  $v_{OSP}$  as function of device mismatch:

$$V_{OSP} \approx V_T \left( \frac{\Delta R_C}{R_C} \left( 1 + \frac{g_m R_E}{\alpha_F} \right) + \frac{\Delta I_S}{I_S} - \frac{g_m R_E}{\alpha_F} \left( \frac{\Delta R_E}{R_E} - \frac{\Delta \alpha_F}{\alpha_F} \right) \right)$$



- Emitter degeneration does not help.
- In fully balanced circuits mean offset should be 0
  - Schematic it is, layout it is not: path connecting RE and RC component devices is not symmetrical!
  - Average offset:  $\mu(v_{OSP}) = -0,75 \text{ mV}$
  - Not corrected: useful to improved dynamic range.
- Random offset std. dev.: yield versus performance:

$$\sigma_{V_{OSP}} \approx V_T \sqrt{\left( \frac{\sigma_{\Delta R_C}}{R_C} \right)^2 \left( 1 + \frac{g_m R_E}{\alpha_F} \right)^2 + \left( \frac{\sigma_{\Delta I_S}}{I_S} \right)^2 + \left( \frac{\sigma_{\Delta R_E}}{R_E} \right)^2 \left( \frac{g_m R_E}{\alpha_F} \right)^2 + \left( \frac{\sigma_{\Delta \alpha_F}}{\alpha_F} \right)^2 \left( \frac{g_m R_E}{\alpha_F} \right)^2} \approx 0,8 \text{ mV rms}$$

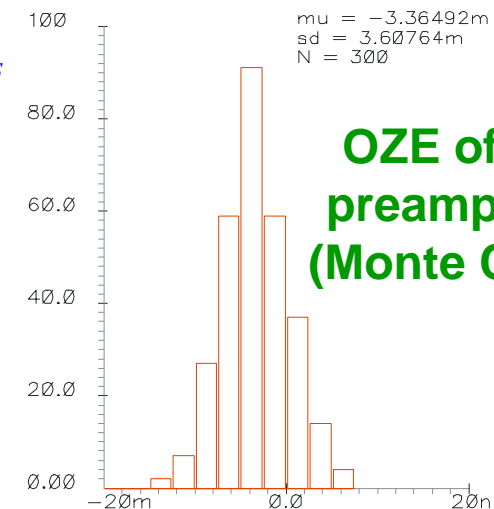
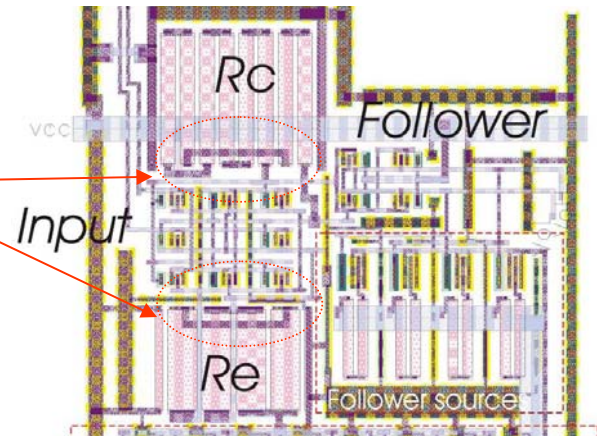
- Total output zero error (OZE):  $v_{OS}$ ,  $i_{OS}$ ,  $R_S$  and DC gain

$A_{DD}(0)$ :

$$OZE_P = A_{DD}(0) IZE_P = A_{DD}(0) (V_{OSP} + 2R_S I_{OSP})$$

$$\sigma_{OZE_P}^2 = A_{DD}^2(0) \left( \sigma_{V_{OSP}}^2 + (2R_S)^2 \sigma_{I_{OSP}}^2 + 2(2R_S) \text{cov}(V_{OSP}, I_{OSP}) \right) \approx \left|_{R_S \ll 5 \text{ K}\Omega} A_{DD}(0) \sigma_{V_{OSP}} \right. = 3.6 \text{ mV rms}$$

$$\mu_{OZE_P} \approx \left|_{R_S \ll 5 \text{ K}\Omega} A_{DD}(0) \mu_{V_{OSP}} \right. = -3.4 \text{ mV}$$



**OZE of the preamplifier (Monte Carlo)**

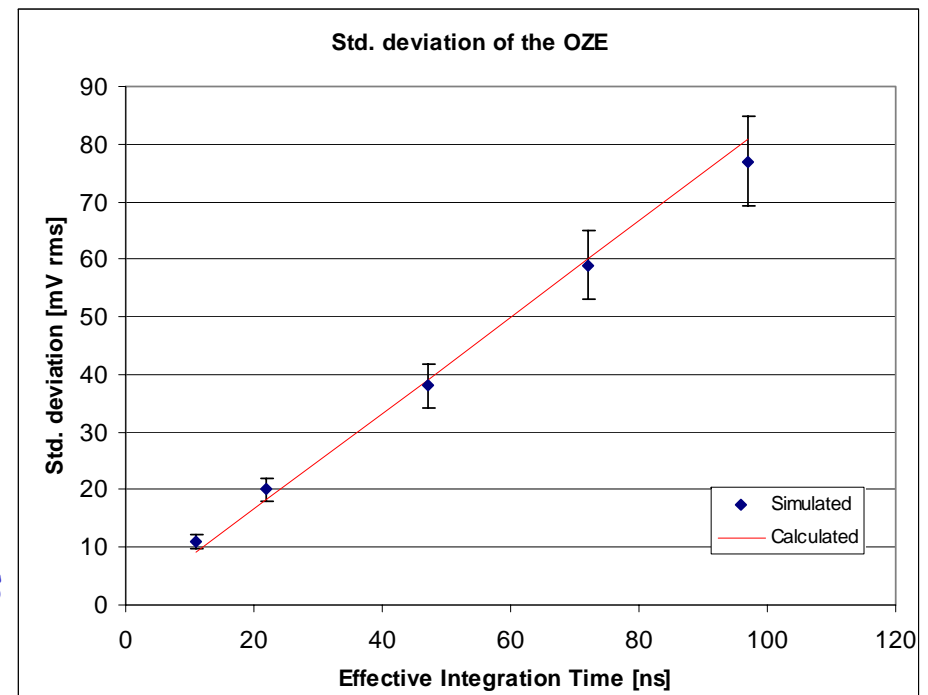
## Offset: integrator

- Main contribution: input differential pair.
- Compute  $v_{OS}$  as in preamplifier:  $\sigma_{V_{OSI}} = 1.2 \text{ mV r.m.s.}$ 
  - Preamplifier low output impedance:  $i_{OSI}$  is not relevant.
- Integrator is switching at 40 MHz: Transient response has to be considered!

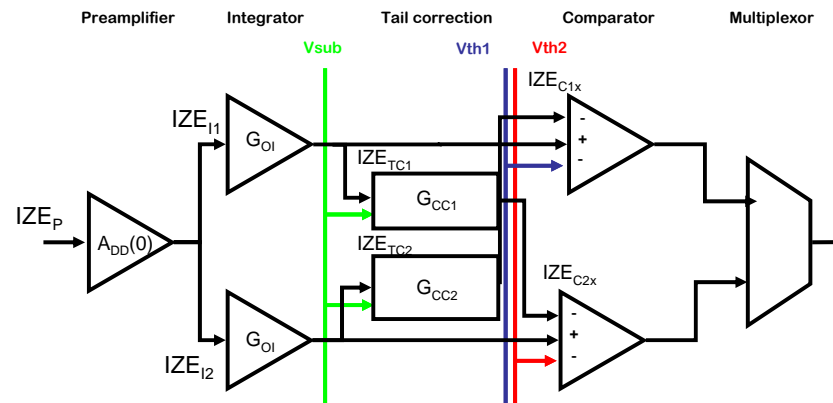
- OZE depends linearly on T
  - For  $T \ll G_{DMO} R_C C_f$ :

$$OZE(T_m) \approx V_{OSI} \frac{T_m}{C_f R_E}$$

- Mismatch Monte Carlo simulations:
  - Compatible within statistical errors



# Offset: full channel



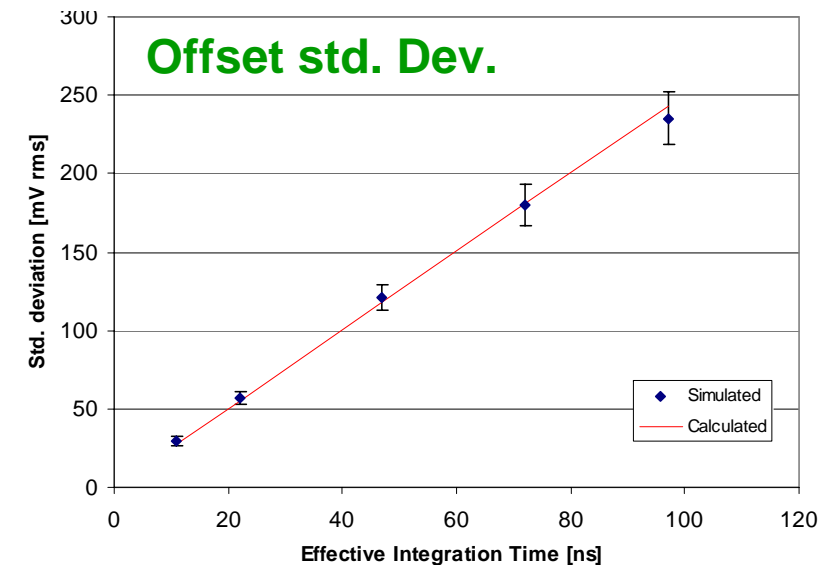
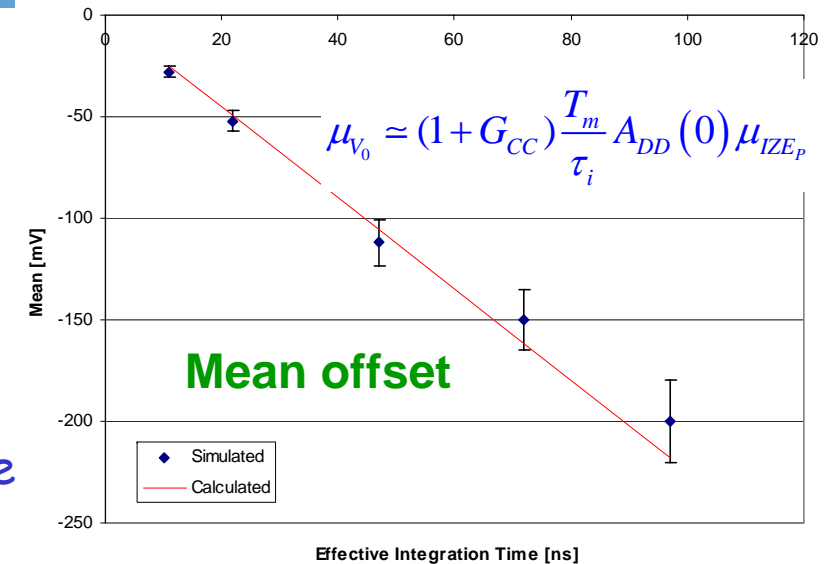
- For the full analogue chain the offset  $V_0$  at the comparator input is:

$$V_0 = G_{OI1} [A_{DD}(0) IZE_P + IZE_{I1}] + G_{CC2} [G_{OI2} [A_{DD}(0) IZE_P + IZE_{I2}] + IZE_{TC2}] + IZE_{C1l} + IZE_{C1h} + IZE_{C1th}$$

- IZE of all the blocks is comparable
- Gain is concentrated on first stages
- Uncorrelated sources

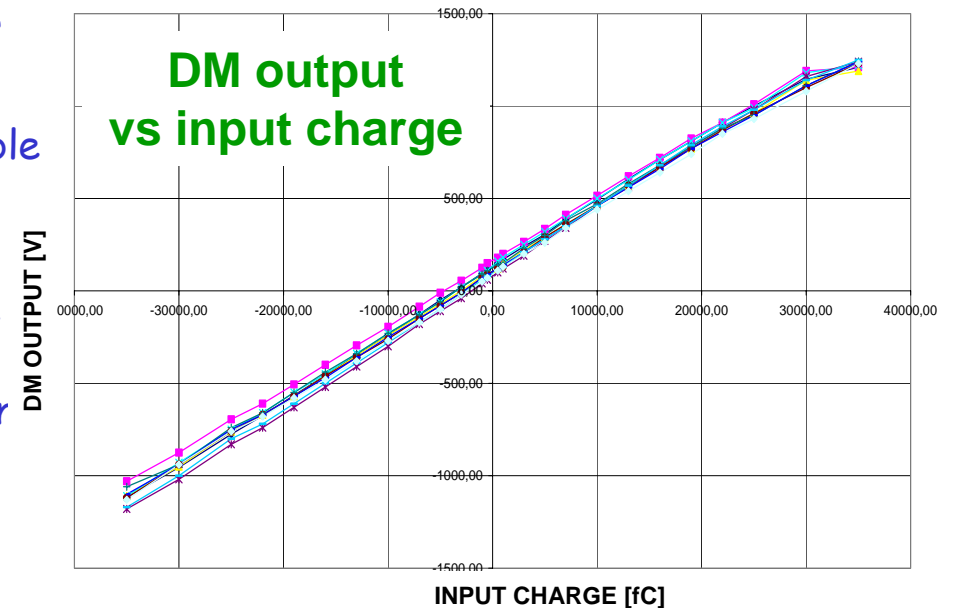
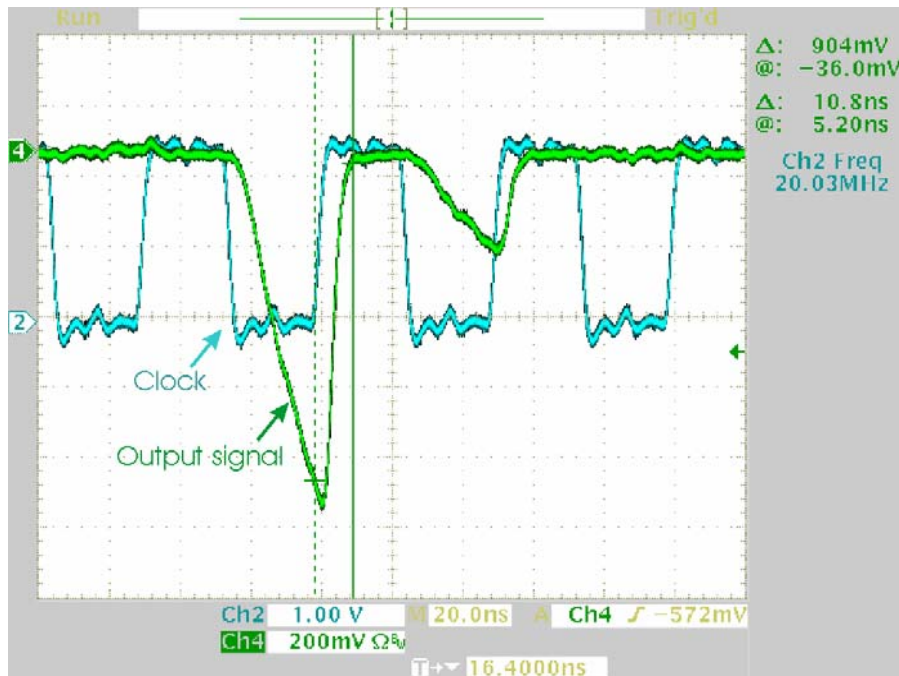
$$\sigma_{V_0}^2 \approx [G_{OI}(1 + G_{CC})]^2 \left[ \sigma_{IZE_P}^2 [A_{DD}(0)]^2 + \sigma_{IZE_I}^2 \right]$$

- Tail correction minimizes apparent offset:
  - Because  $G_{CC} \ll 0$ .
- Calculations ok with Monte Carlo simulations.
- Temperature dependence:  $\frac{\partial \mu_{V_0}}{\partial T} = -15 \frac{\mu V}{K}$      $\frac{\partial \sigma_{V_0}}{\partial T} = 18 \frac{\mu V}{K}$



# Characterization of building blocks: integrator

- Good agreement except for mean offset.
- Post layout simulations including parasitic R and C do not show systematic offset.
- Offset measurement of the channel are compatible with some systematic offset, *but small*.
- Seems to be a true charge injection effect:
  - Clock or parasitic capacitance unbalance (channel).
  - Coupling at input pad (only block test circuit).
- Systematic injection: not a problem for resolution

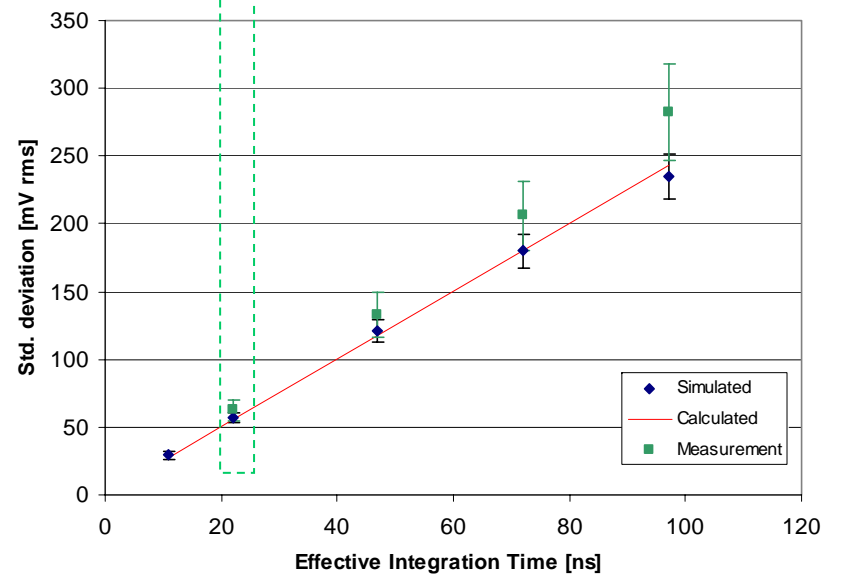
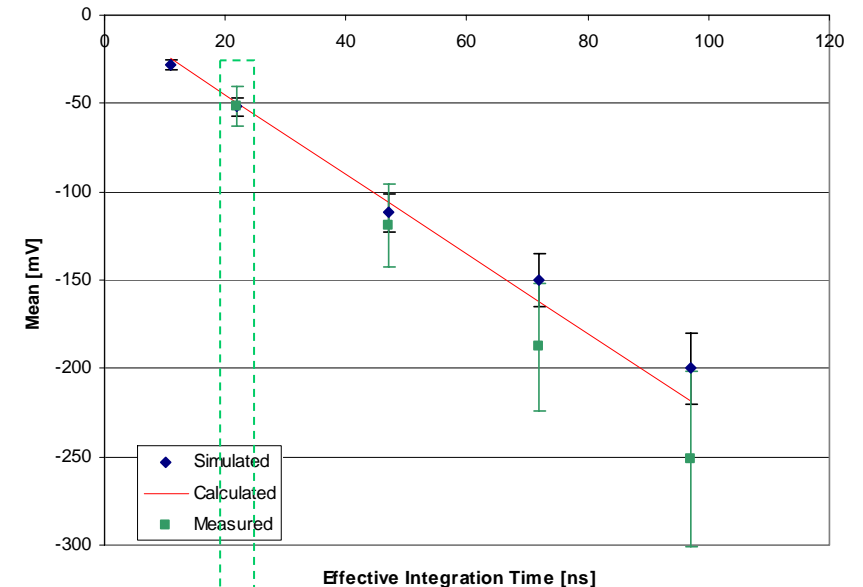
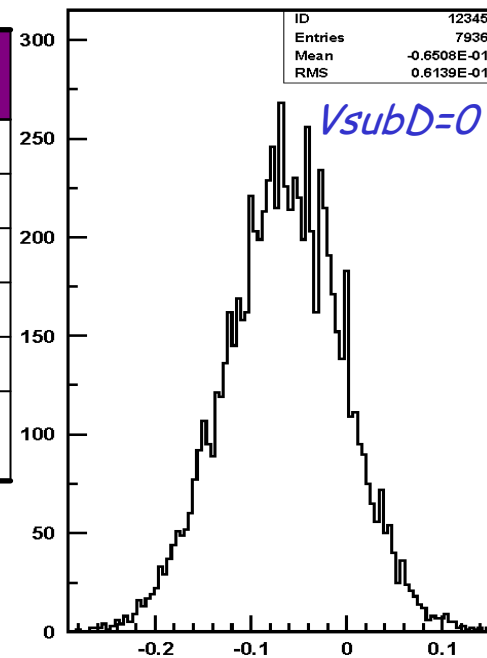


	Simulation / calculation	Measurement
Mean offset $\mu(v_{0SI})$	0	-1,3 mV
Std dev offset $\sigma(v_{0SI})$	1,2 mV rms	1,1 mV rms
Time constant ( $R_E C_p$ )	1,6 ns	1,6 ns
Reset time @ 1 V	< 10 ns	5 ns
Linearity error $ VoD  < 300$ mV	< 0,1 %	< 1 %
Temperature coefficient	- 150 ppm/C	- 200 ppm/C

# System performance: offset and yield

- Good agreement with calculations for chip soldered in VFE cards (perfect at  $T=25$  ns).
- Discrepancies are higher for measurements in test socket (charge injection).
- A yield of 80 % is obtained.
- Less 1 % are rejected for high offset.

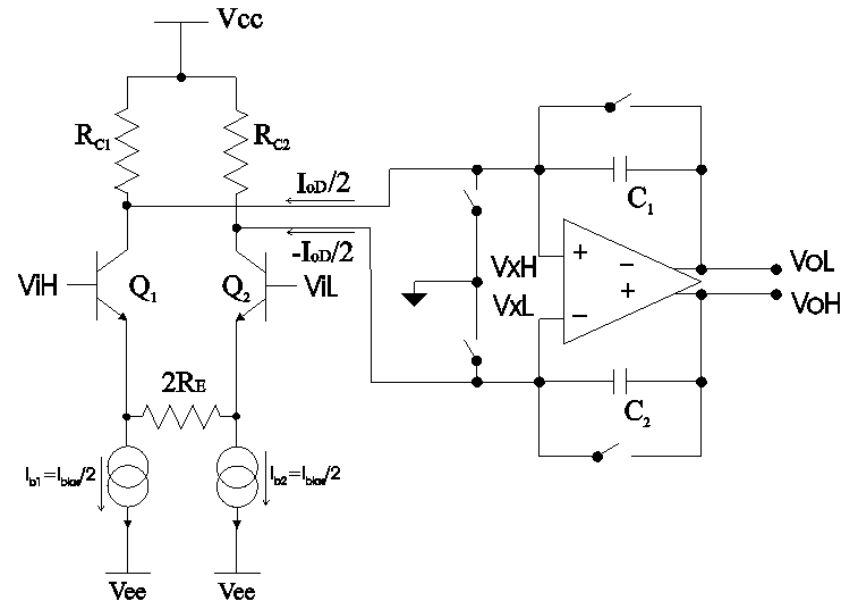
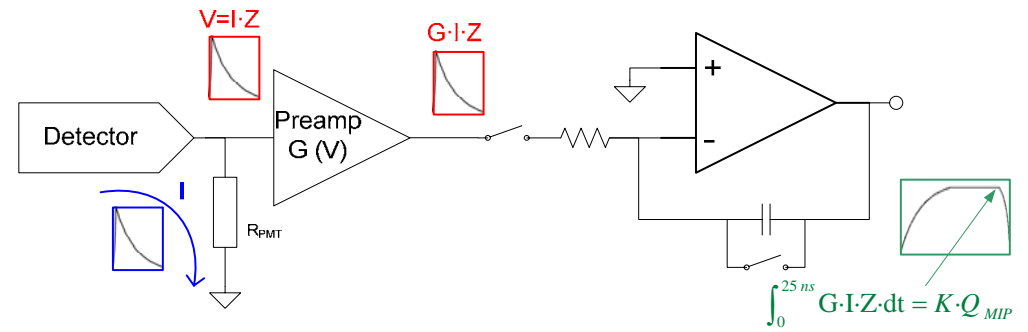
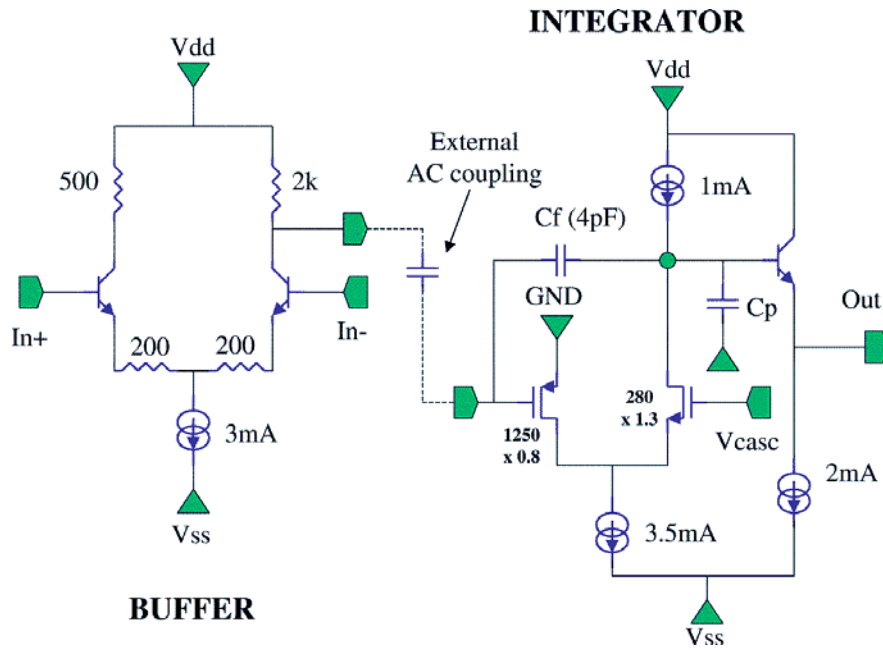
Total	1311	100 %
Digital Error	112	8,5 %
Bias problem	38	3 %
Gen. failure	29	2,2 %
Dead channel	73	5,6 %
High offset	9	0,7 %
Pass	1050	80 %



# Extrapolation SPD to ECAL

- Gain:  $V$  (int. output) /  $Q$

$$G_Q \equiv \frac{v_{oD}(t = T_m)}{-Q_{MIP}} \approx R_{PMT} A \frac{1}{R_E C_f} \left( 1 - e^{-\frac{T_m}{\tau}} \right)_{T_m = 25ns}$$



## Conclusions

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- Std deviation is about 55 mV rms
- Gain:  $V$  (int. output) /  $Q$ 
  - 0,36 mV / ADC count
  - 5 fC / ADC count
  - 75 uV / fC: gain in charge is 16 higher in SPD
- Resistor converting PMT current to voltage is  $470/50 = 9,4$
- Voltage gain is only about factor 2 large in SPD
- Extrapolated "random" offset should be 27 mV rms!
  - It is probably smaller in PS
  - Improve by a factor 3 (technology, layout)
  - AC coupling, differentiator...
- Charge injection by switches is almost negligible
  - Thanks to differential circuitry and integration